



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,603

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND

PACKAGING OF FLIP CHIP

CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6862

Examiner: S. Geyer

Group Art Unit: 2812

Attorney Docket No.: 2269-4974.2US

(00-0693.02/US)

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NOTICE OF EXPRESS MAILING

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Person making Deposit: _____ Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 19 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 20 of this paper;

Corrections to the drawings are summarized on page 25 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 26 of this paper.